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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I²C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	20K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 12x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101ljafa-v0

4.6 Cautions on 1-Bit Manipulation In struction for Port Register n (Pn)

When a 1-bit manipulation instruction is executed on a port that provides both input and output functions, the output latch value of an input port that is not subject to manipulation may be written in addition to the targeted bit.

Therefore, it is recommended to rewrite the output latch when switching a port from input mode to output mode.

<Example> When P10 is an output port, P11 to P17 are input ports (all pin statuses are high level), and the port latch value of port 1 is 00H, if the output of output port P10 is changed from low level to high level via a 1-bit manipulation instruction, the output latch value of port 1 is FFH.

Explanation: The targets of writing to and reading from the Pn register of a port whose PMnm bit is 1 are the output latch and pin status, respectively.

A 1-bit manipulation instruction is executed in the following order in the 78K0/LG2.

<1> The Pn register is read in 8-bit units.
<2> The targeted one bit is manipulated.
<3> The Pn register is written in 8-bit units.

In step <1>, the output latch value (0) of P10, which is an output port, is read, while the pin statuses of P11 to P17, which are input ports, are read. If the pin statuses of P11 to P17 are high level at this time, the read value is FEH.

The value is changed to FFH by the manipulation in <2>.

FFH is written to the output latch by the manipulation in <3>.

Figure 4-42. Bit Manipu lation Instruction (P10)

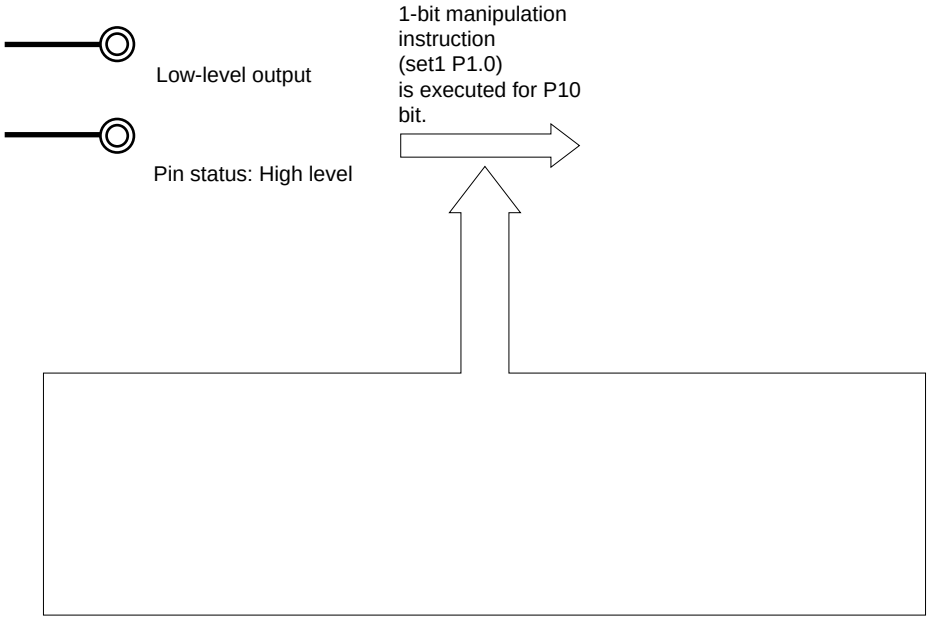
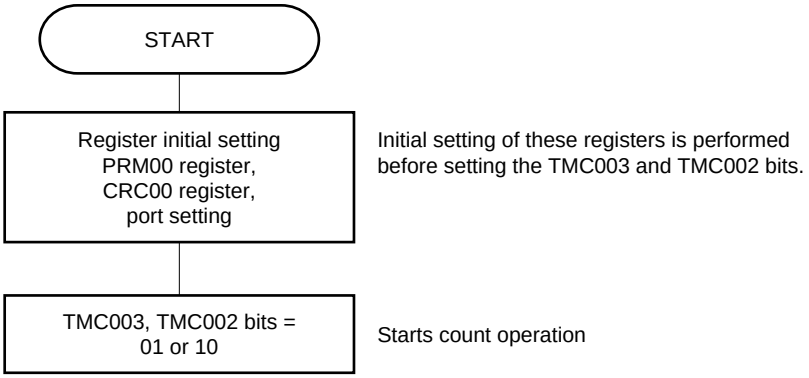
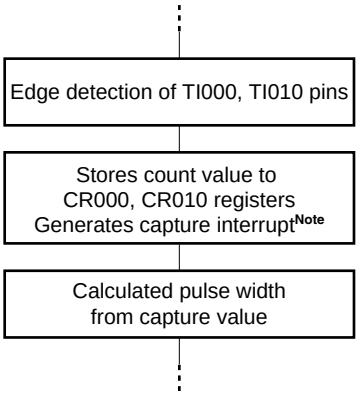


Figure 6-53. Example of Software Processing for Pulse Width Measurement (2/2)

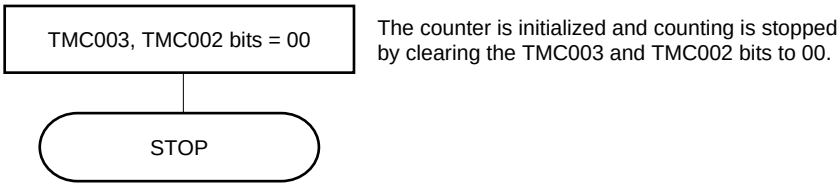
<1> Count operation start flow



<2> Capture trigger input flow



<3> Count operation stop flow



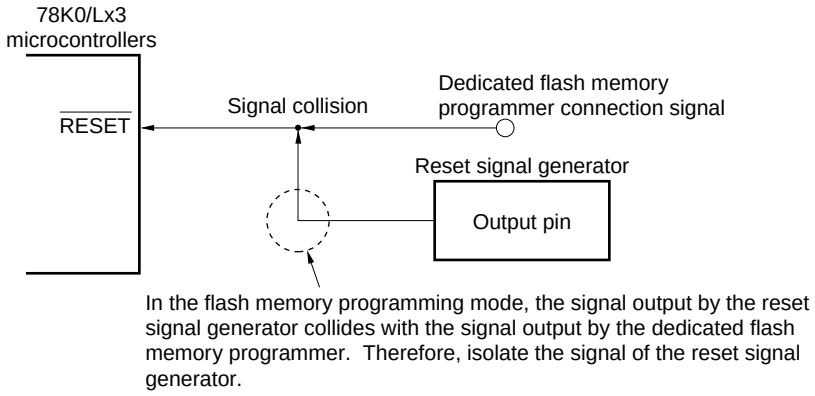
Note The capture interrupt signal (INTTM000) is not generated when the reverse-phase edge of the TI000 pin input is selected to the valid edge of CR000.

28.6.3 $\overline{\text{RESET}}$ pin

If the reset signal of the dedicated flash memory programmer is connected to the $\overline{\text{RESET}}$ pin that is connected to the reset signal generator on the board, signal collision takes place. To prevent this collision, isolate the connection with the reset signal generator.

If the reset signal is input from the user system while the flash memory programming mode is set, the flash memory will not be correctly programmed. Do not input any signal other than the reset signal of the dedicated flash memory programmer.

Figure 28-9. Signal Collision ($\overline{\text{RESET}}$ Pin)



28.6.4 Port pins

When the flash memory programming mode is set, all the pins not used for flash memory programming enter the same status as that immediately after reset. If external devices connected to the ports do not recognize the port status immediately after reset, the port pin must be connected to V_{DD} or V_{SS} via a resistor.

28.6.5 REGC pin

Connect the REGC pin to GND via a capacitor (0.47 to 1 μF: recommended) in the same manner as during normal operation.

28.6.6 Other signal pins

Connect X1 and X2 in the same status as in the normal operation mode when using the on-board clock.

To input the operating clock from the dedicated flash memory programmer, however, connect CLK of the programmer to EXCLK/X2/P122.

Cautions 1. Only the internal high-speed oscillation clock (f_{RH}) can be used when CSI10 is used.

2. The X1 clock (f_X), external main system clock (f_{EXCLK}), or internal high-speed oscillation clock (f_{RH}) can be used when UART6 is used.

28.6.7 Power supply

To use the supply voltage output of the flash memory programmer, connect the V_{DD} pin to V_{DD} of the flash memory programmer, and the V_{SS} pin to GND of the flash memory programmer.

To use the on-board supply voltage, connect in compliance with the normal operation mode.

However, be sure to connect the V_{DD} and V_{SS} pins to V_{DD} and GND of the flash memory programmer to use the power monitor function with the flash memory programmer, even when using the on-board supply voltage.

Supply the same other power supplies (AV_{REF} and AV_{SS}) as those in the normal operation mode.

Instruction Group	Mnemonic	Operands	Bytes	Clocks		Operation	Flag
				Note 1	Note 2		Z AC CY
8-bit operation	**OR**	A, #byte	2	4	–	A ← A ∨ byte	×
		saddr, #byte	3	6	8	(saddr) ← (saddr) ∨ byte	×
		A, r Note 3	2	4	–	A ← A ∨ r	×
		r, A	2	4	–	r ← r ∨ A	×
		A, saddr	2	4	5	A ← A ∨ (saddr)	×
		A, !addr16	3	8	9	A ← A ∨ (addr16)	×
		A, [HL]	1	4	5	A ← A ∨ (HL)	×
		A, [HL + byte]	2	8	9	A ← A ∨ (HL + byte)	×
		A, [HL + B]	2	8	9	A ← A ∨ (HL + B)	×
		A, [HL + C]	2	8	9	A ← A ∨ (HL + C)	×
	XOR	A, #byte	2	4	–	A ← A ⊻ byte	×
		saddr, #byte	3	6	8	(saddr) ← (saddr) ⊻ byte	×
		A, r Note 3	2	4	–	A ← A ⊻ r	×
		r, A	2	4	–	r ← r ⊻ A	×
		A, saddr	2	4	5	A ← A ⊻ (saddr)	×
		A, !addr16	3	8	9	A ← A ⊻ (addr16)	×
		A, [HL]	1	4	5	A ← A ⊻ (HL)	×
		A, [HL + byte]	2	8	9	A ← A ⊻ (HL + byte)	×
		A, [HL + B]	2	8	9	A ← A ⊻ (HL + B)	×
		A, [HL + C]	2	8	9	A ← A ⊻ (HL + C)	×
	CMP	A, #byte	2	4	–	A – byte	× × ×
		saddr, #byte	3	6	8	(saddr) – byte	× × ×
		A, r Note 3	2	4	–	A – r	× × ×
		r, A	2	4	–	r – A	× × ×
		A, saddr	2	4	5	A – (saddr)	× × ×
		A, !addr16	3	8	9	A – (addr16)	× × ×
		A, [HL]	1	4	5	A – (HL)	× × ×
		A, [HL + byte]	2	8	9	A – (HL + byte)	× × ×
		A, [HL + B]	2	8	9	A – (HL + B)	× × ×
		A, [HL + C]	2	8	9	A – (HL + C)	× × ×

Notes 1. When the internal high-speed RAM area is accessed or for an instruction with no data access

2. When an area except the internal high-speed RAM area is accessed

3. Except “r = A”

Remarks 1. One instruction clock cycle is one cycle of the CPU clock (f_{CPU}) selected by the processor clock control register (PCC).

2. This clock cycle applies to the internal ROM program.

Caution The pins mounted depend on the product. Refer to Caution 2 at the beginning of this chapter.

(e) AUTOCSI (Master mode, $\overline{\text{SCKA0}}$... internal clock output)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
$\overline{\text{SCKA0}}$ cycle time	t_{KCY3}	4.0 V ≤ V_{DD} ≤ 5.5 V		600			ns
		2.7 V ≤ V_{DD} < 4.0 V		1200			ns
		1.8 V ≤ V_{DD} < 2.7 V		1800			ns
$\overline{\text{SCKA0}}$ high-/low-level width	t_{KH3}, t_{KL3}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY3}/2 – 50			ns
		2.7 V ≤ V_{DD} < 4.0 V		t_{KCY3}/2 – 100			ns
		1.8 V ≤ V_{DD} < 2.7 V		t_{KCY3}/2 – 200			ns
SIA0 setup time (to $\overline{\text{SCKA0}}$↑)	t_{SIK3}	2.7 V ≤ V_{DD} ≤ 5.5 V		100			ns
		1.8 V ≤ V_{DD} < 2.7 V		200			ns
SIA0 hold time (from $\overline{\text{SCKA0}}$↑)	t_{KSI3}			300			ns
Delay time from $\overline{\text{SCKA0}}$↓ to SOA0 output	t_{KSO3}	C = 100 pF Note	4.0 V ≤ V_{DD} ≤ 5.5 V			200	ns
			2.7 V ≤ V_{DD} < 4.0 V			300	ns
			1.8 V ≤ V_{DD} < 2.7 V			400	ns

Note C is the load capacitance of the $\overline{\text{SCKA0}}$ and SOA0 output lines.

(f) AUTOCSI (Slave mode, $\overline{\text{SCKA0}}$... external clock input)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
$\overline{\text{SCKA0}}$ cycle time	t_{KCY4}	4.0 V ≤ V_{DD} ≤ 5.5 V		600			ns
		2.7 V ≤ V_{DD} < 4.0 V		1200			ns
		1.8 V ≤ V_{DD} < 2.7 V		1800			ns
$\overline{\text{SCKA0}}$ high-/low-level width	t_{KH4}, t_{KL4}	4.0 V ≤ V_{DD} ≤ 5.5 V		300			ns
		2.7 V ≤ V_{DD} < 4.0 V		600			ns
		1.8 V ≤ V_{DD} < 2.7 V		900			ns
SIA0 setup time (to $\overline{\text{SCKA0}}$↑)	t_{SIK4}			100			ns
SIA0 hold time (from $\overline{\text{SCKA0}}$↑)	t_{KSI4}			2/f_W+100			ns
Delay time from $\overline{\text{SCKA0}}$↓ to SOA0 output	t_{KSO4}	C = 100 pF Note	4.0 V ≤ V_{DD} ≤ 5.5 V			2/f_W+100	ns
			2.7 V ≤ V_{DD} < 4.0 V			2/f_W+200	ns
			1.8 V ≤ V_{DD} < 2.7 V			2/f_W+300	ns
$\overline{\text{SCKA0}}$ rise/fall time	t_{R4}, t_{F4}					1000	ns

Note C is the load capacitance of the SOA0 output line.

LVI Circuit Characteristics (T_A = –40 to +85°C, $V_{POC} \le V_{DD} \le$ 5.5 V, V_{SS} = 0 V)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	Supply voltage level	V_{LVI0}		4.14	4.24	4.34	V
		V_{LVI1}		3.99	4.09	4.19	V
		V_{LVI2}		3.83	3.93	4.03	V
		V_{LVI3}		3.68	3.78	3.88	V
		V_{LVI4}		3.52	3.62	3.72	V
		V_{LVI5}		3.37	3.47	3.57	V
		V_{LVI6}		3.22	3.32	3.42	V
		V_{LVI7}		3.06	3.16	3.26	V
		V_{LVI8}		2.91	3.01	3.11	V
		V_{LVI9}		2.75	2.85	2.95	V
		V_{LVI10}		2.60	2.70	2.80	V
		V_{LVI11}		2.45	2.55	2.65	V
		V_{LVI12}		2.29	2.39	2.49	V
		V_{LVI13}		2.14	2.24	2.34	V
		V_{LVI14}		1.98	2.08	2.18	V
		V_{LVI15}		1.83	1.93	2.03	V
	External input pin[Note 1]	EXLVI	EXLVI < V_{DD}, 1.8 V ≤ V_{DD} ≤ 5.5 V	1.11	1.21	1.31	V
Minimum pulse width		t_{LW}		200			μs
Operation stabilization wait time[Note 2]		t_{LWAIT}				10	μs

Notes 1. The EXLVI/P120/INTP0 pin is used.

2. Time required from setting bit 7 (LVION) of the low-voltage detection register (LVIM) to 1 to operation stabilization.

Remark $V_{LVI(n-1)} > V_{LVIn}$: n = 1 to 15

LVI Circuit Timing

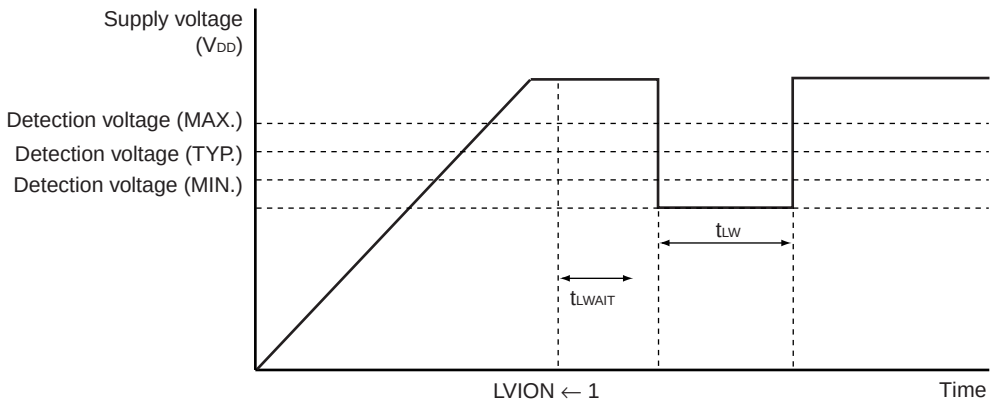
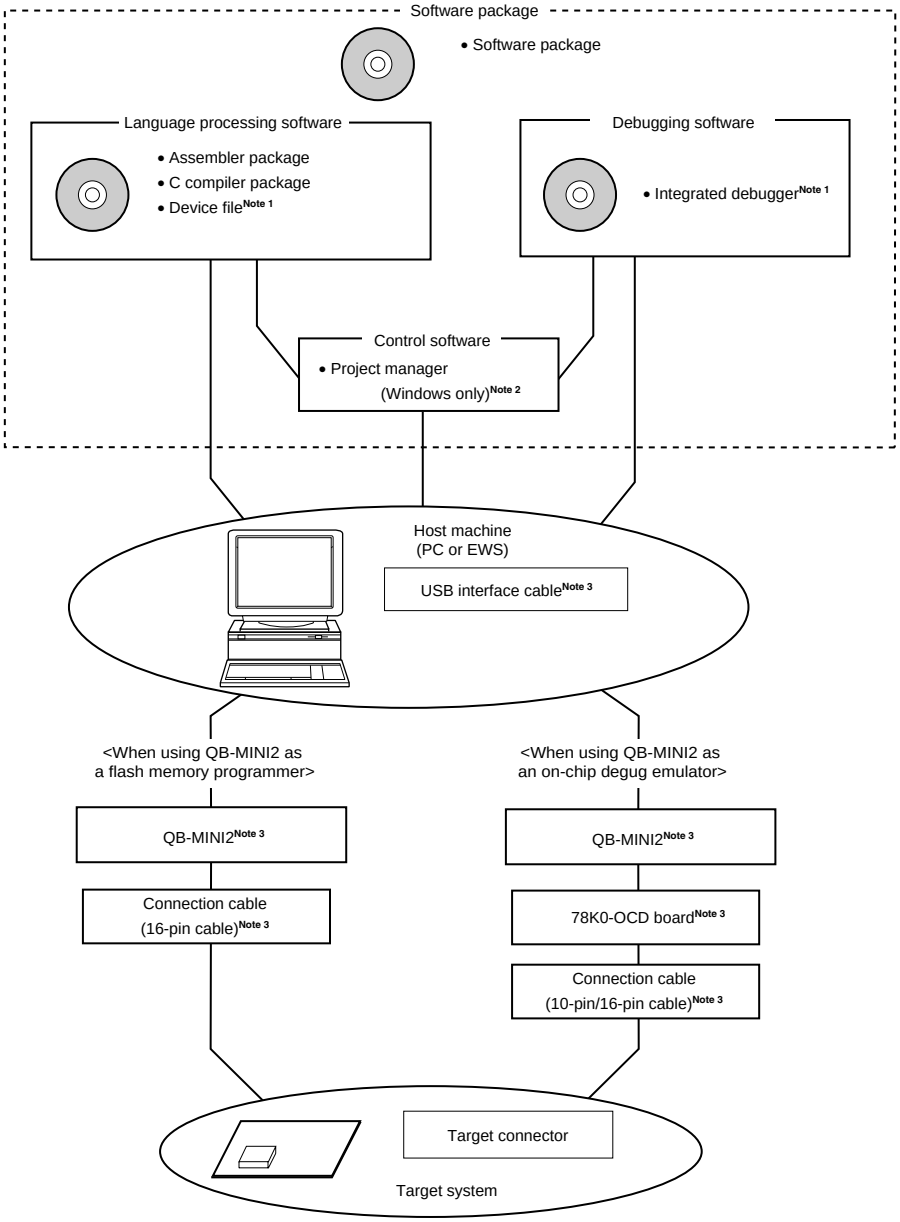


Figure A-1. Development Tool Configuration (2/2)

(2) When using the on-chip debug emulator with programming function QB-MINI2



Notes 1. Download the device file for 78K0/Lx3 microcontrollers (DF780495) and the integrated debugger ID78K0-QB from the download site for development tools (http://www.renesas.com/micro/en/ods/).

2. The project manager PM+ is included in the assembler package.
PM+ cannot be used other than with Windows.

3. QB-MINI2 is supplied with USB interface cable, connection cables (10-pin cable and 16-pin cable), and 78K0-OCD board. Any other products are sold separately. In addition, download the software for operating the QB-MINI2 from the download site for development tools
(http://www.renesas.com/micro/en/ods/).